Panasonic INDUSTRY

High fluidity

Excellent fillability for narrow gap/pitch

Reduced void/bleed

Applications
IC Package/Mobile
High-density advanced IC packages (BGA, CSP)

LEXCM DF

CV5300 series

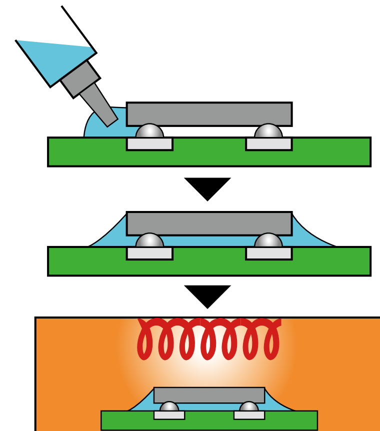
Capillary underfill (CUF) semiconductor encapsulation materials

High capillary flow rate fills narrow gaps without voiding.

Line-up

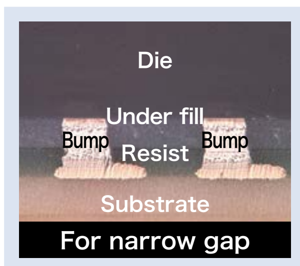
Features

1. Compatible with narrow gap
2. Uniform penetration
3. High-speed fillability
4. Compatible with low-k film
5. High moisture reflow resistance

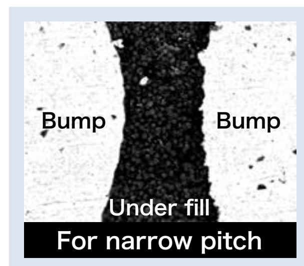


Part Number	Features
CV5300 series	**High fluidity, Short-time curing**

Excellent fillability for narrow gap/pitch

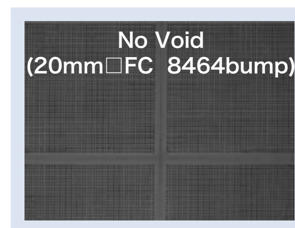


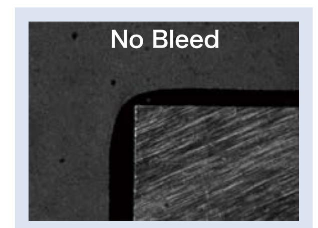
For narrow gap



For narrow pitch

Reduced void/bleed





General properties

Item	Unit	CV5300 series
Filler size Max	μm	1
C.T.E.	ppm/℃	33
Tg (TMA)	℃	110
Modulus	GPa	7

Please see our website for Notes before you use.

The written property values are just an example of our product line-up. Please contact us for details.

industrial.panasonic.com/ww/electronic-materials

Panasonic Industry CV5300

Panasonic Industry Co., Ltd. Electronic Materials Business Division

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